

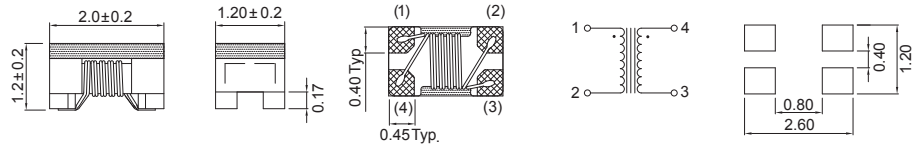
SCM2012F Series (SHIELDED)

■ SMD Molded Wire Wound Ferrite Chip

MECHANICAL DIMENSIONS



SCM2012F



Recommended Patterns

unit: mm

ELECTRICAL SPECIFICATION

Part Number	Impedance @100MHz (Ω)	Rated Current (mA) Max.	DCR (Ω) Max.	Rated Voltage (Vdc)	Withstand Voltage (Vdc)	Insulation Resistance @125VDC (M.Ω) Min.
SCM2012F-670M-I-LRH	67	400	0.25			
SCM2012F-900M-I-LRH	90	330	0.35			
SCM2012F-121M-I-LRH	120	370	0.30			
SCM2012F-181M-I-LRH	180	330	0.35	50	125	10
SCM2012F-261M-I-LRH	260	300	0.40			
SCM2012F-371M-I-LRH	370	280	0.45			
SCM2012F-601M-I-LRH	600	240	0.60			

- Tolerance: M=±20%
- Small size, low profile.
- Various common mode impedance from 67Ω to 600Ω.
- Operating Temp.: -40°C to +125°C
- Storage temperature: -40°C to +125°C
- Temperature rise: 15°C
- Impedance measured using the HP4291B RF Impedance Analyzer.
- DCR measured using the 16502 milli-ohm meter.

APPLICATIONS

- Common mode noise suppression of signal lines in high speed and high-density digital equipment such as personal computers and peripherals.
- Suitable for differential signal line such as USB2.0, IEEE1394 and LVDS, Capable of high speed signal transmission without distortion due to its high coupling.

CHARACTERISTIC CURVE

